

ABSTRACT OF THE DISCLOSURE

A bonding pad structure and fabrication method thereof.
A bonding pad is substantially surrounded and insulated by a
dielectric layer, wherein the bonding pad is formed of at least
5 one first conductive layer having a wiring layer with a stripe
layout and a first edge portion, a second conductive layer having
a wire bonding portion and a second edge portion and a plurality
of plugs electrically connecting the wiring layer and the wire
bonding portion. A conductive structure of an array of metal
10 plugs or a metal damascene structure is formed to connect the
first edge portion and the second edge portion, thereby
preventing burn out of the first edge portion during an ESD event.